

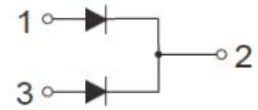


Features

- High current capability
- Low forward voltage drop
- Low power loss, high efficiency
- High surge capability
- High temperature soldering guaranteed
- Mounting position: any



TO252-2L



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MBRD1040CT- MBRD10200CT	TO-252-2L	MBRD10*	2500

*:From 40-200CT

Maxmim Ratings Electrcal Charcteristics

Ratings at 25°C ambient temperature unless otherwise specified

Characteristics	Symbol	MBRD 1040CT	MBRD 1045CT	MBRD 1060CT	MBRD 10100CT	MBRD 10150CT	MBRD 10200CT	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	40	45	60	100	150	200	V
Maximum RMS voltage	V_{RMS}	28	32	42	70	105	140	V
Maximum DC Blocking Voltage	V_{DC}	40	45	60	100	150	200	V
Maximum Average Forward Rectified Current Per diode Per device	$I_{F(AV)}$	5 10						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) Per leg	I_{FSM}	100						A
Max Instantaneous Forward Voltage at 5.0 A Per leg	V_F	0.70		0.75	0.85	0.90	0.92	V
Maximum DC Reverse Current at Rated DC Reverse Voltage $T_a = 25^\circ\text{C}$ $T_a = 125^\circ\text{C}$	I_R	0.1 20			0.05 20			mA
Typical Junction Capacitance ⁽¹⁾	C_j	600		400				pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	35						°C/W
Operating Junction Temperature Range	T_j	-55 ~ +150				-55 ~ +175		°C
Storage Temperature Range	T_{stg}	-55 ~ +150				-55 ~ +175		°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 10cmX10cmX1mm copper pad areas.



Typical Characteristics

Fig.1 TYPICAL FORWARD CURRENT DERATING CURVE

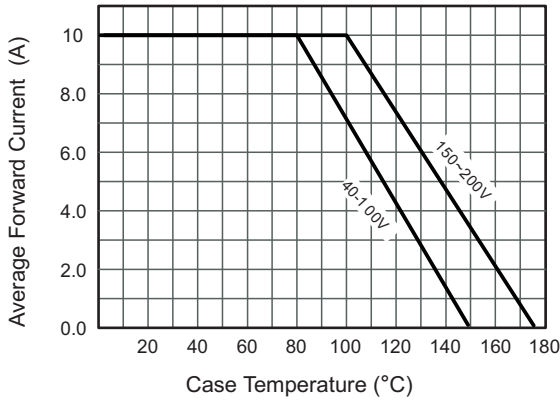


Fig.2 Typical Reverse Characteristics

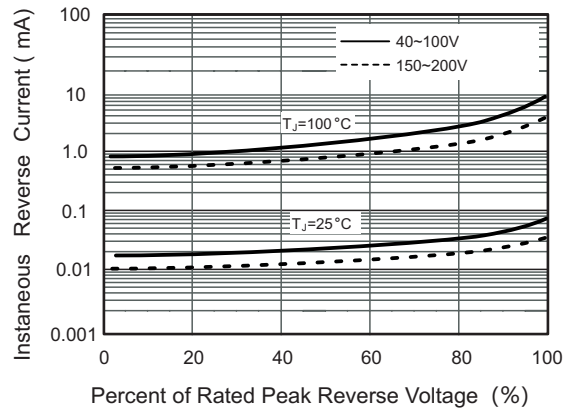


Fig.3 Typical Forward Characteristic

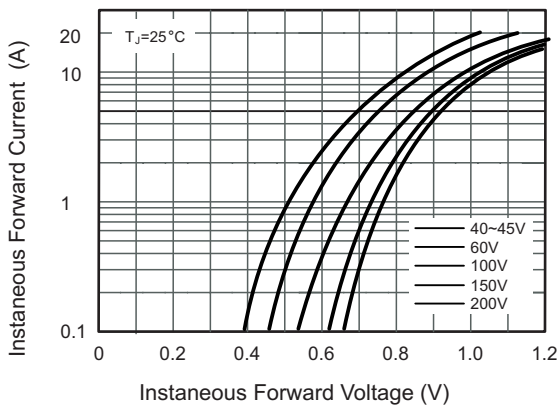


Fig.4 Typical Junction Capacitance

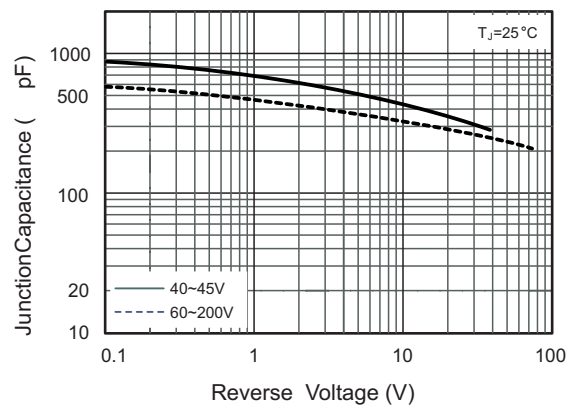


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

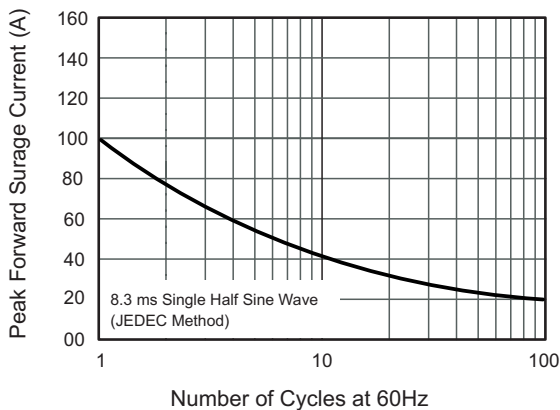
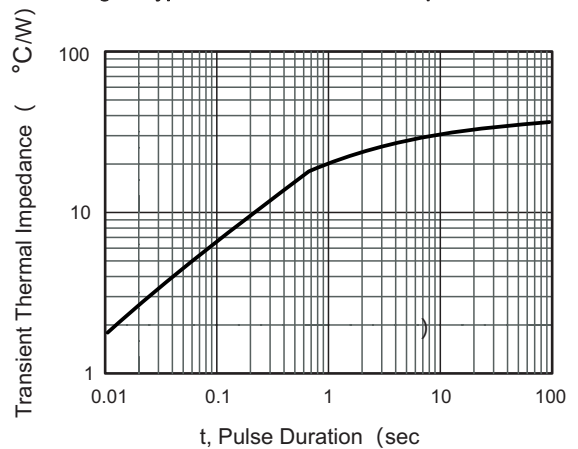
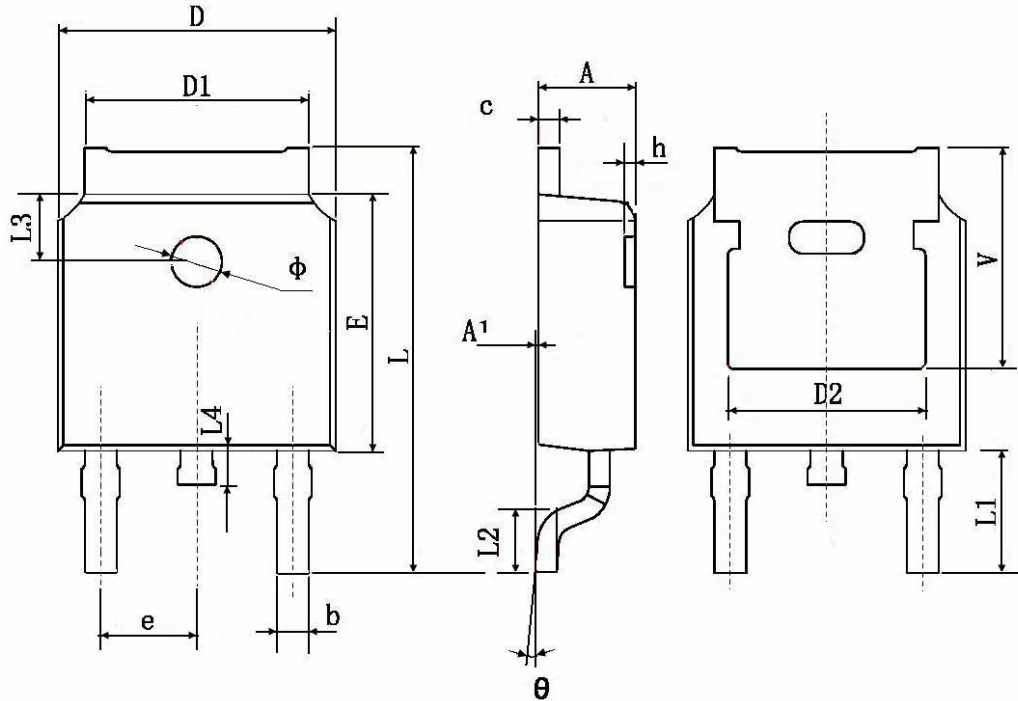


Fig.6- Typical Transient Thermal Impedance





TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
phi	1.100	1.300	0.043	0.051
theta	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012



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